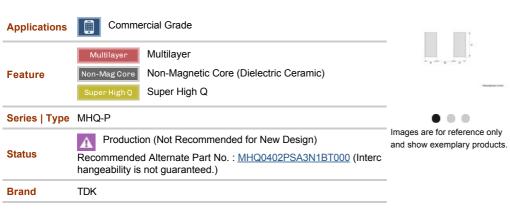




## Inductors (Coils)

| Product Top Page | Search by Part No. | Search by Characteristics | Cross Reference | Catalog | Tech Notes | ▼ more |
|------------------|--------------------|---------------------------|-----------------|---------|------------|--------|

## MHQ0402P3N1BT000

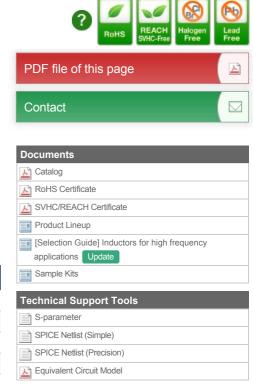


| Size                         |                  |
|------------------------------|------------------|
| Length(L)                    | 0.44mm ±0.02mm   |
| Width(W)                     | 0.24mm ±0.02mm   |
| Thickness   Height           | 0.24mm ±0.02mm   |
| Recommended Land Pattern (A) | 0.15mm to 0.20mm |
| Recommended Land Pattern (B) | 0.20mm Nom.      |
| Recommended Land Pattern (C) | 0.18mm to 0.20mm |

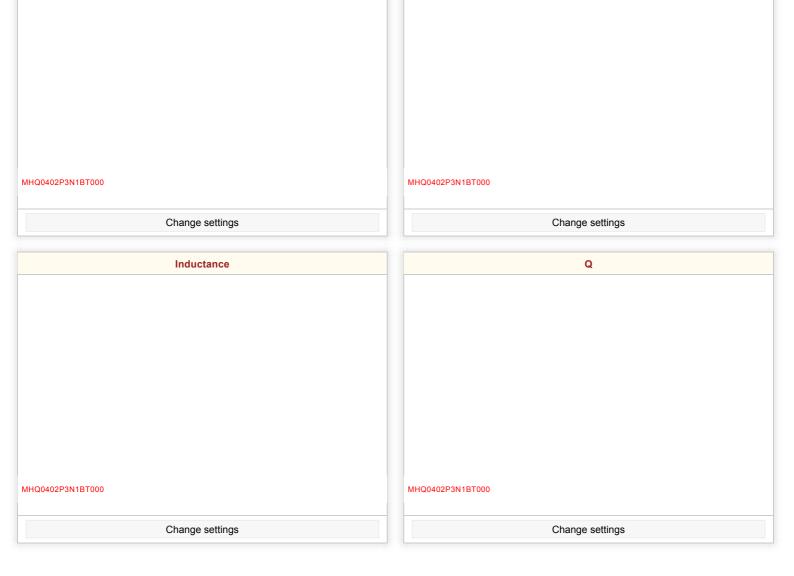
| Electrical Characteristics     | ctrical Characteristics |  |  |
|--------------------------------|-------------------------|--|--|
| Inductance                     | 3.1nH ±0.1nH at 500MHz  |  |  |
| Rated Current                  | 200mA                   |  |  |
| DC Resistance [Typ.]           | 260mΩ                   |  |  |
| DC Resistance [Max.]           | 500mΩ                   |  |  |
| Self Resonant Frequency [Min.] | 5GHz                    |  |  |
| Self Resonant Frequency [Typ.] | 7.9GHz                  |  |  |
| Q [Min.]                       | 10 at 500MHz            |  |  |
| Q [Typ.]                       | 13 at 500MHz            |  |  |

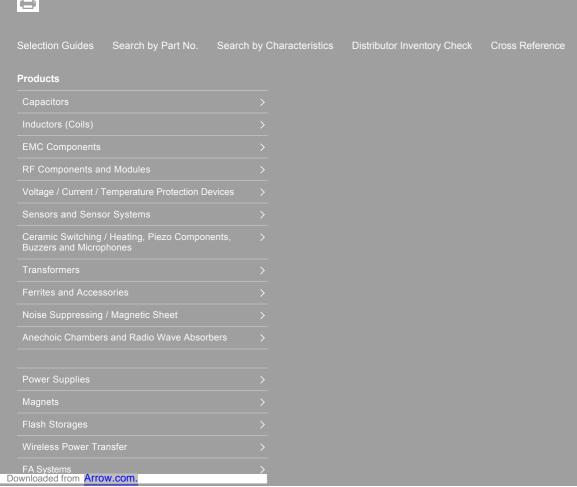
| ner   |                                    |  |
|---|------------------------------------|--|
| Operating Temp. Range (Including Self-Temp. Rise) | -55 to 125°C                       |  |
| Soldering Method                                  | Reflow                             |  |
| AEC-Q200  | No                                 |  |
| Packing   | Punched (Paper)Taping [180mm Reel] |  |
| Package Quantity                                  | 20000pcs                           |  |
| Weight  | 0.00011g                           |  |

## Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)



**Impedance** 





Micro Modules (Substrates with Built-in ICs, Products > Utilizing with SESUB) **Application Guides Technical Support** 

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